

Wire Bonder introduction

**K&S Ball bonder series: 8020/ 8028/
8028S/ 8028PPS**

Wire Bonder Capability for K&S 8028PPS

Bonding Area (X*Y)	50 mm (X) by 65 mm (Y) (2.0" (X) by 2.56" (Y))
Wire Capacity	3500 wire per process program
Wire Length	0.51 to 7.62 mm (0.020" to 0.300")
Loop Height	0.10 to 0.64 mm (0.004" to 0.025")
Bond Height Differential	2.3 mm (0.090")
Wire Diameter	20 to 38 micron (0.8 to 1.5 mil)
Bond Pad Size	Minimum 50 micron
Substrate Material	Normal

Wire Bonding Characteristic for K&S 8028PPS :

Characteristic	micron	Mils	# of wire diameters
Loop Height Variation	+/- 25.4	+/- 1.0	+/- 1.0
Wire Straightness (+/- 1% wire length for wires > 100 mils)	+/- 25.4	+/- 1.0	+/- 1.0
Ball Concentricity	5.0 TIR	0.2 TIR	0.5 TIR
Ball Size Repeatability (Squashed)	+/- 3.5	+/- 0.14	N/A
Bond Placement Repeatability	+/- 3.5	+/- 0.14	N/A
Crescent Bond Squash (one sigma) Length Range: 1 to 3 wire diameters	Width Range: 2 to 5 wire diameters		
Bond Pull Cpk >= 1.67			
Ball Shear Cpk >= 1.33			